said stacked circuit board being formed with insulated circuit boards, in which are packaged electronic circuits that include wiring patterns, stacked in multiple layers in the diametral direction perpendicular to the length direction of the microminiature image pickup device and having a cavity formed as an indentation in the diametral direction thereof;

a first electronic component mounted in said cavity, and a second electronic component mounted on the surface of said stacked circuit board.

2. (Amended) Microminiature image pickup device described in Claim 1 wherein said first electronic component is connected to a wiring pattern formed on the bottom surface of said cavity.

3. (Amended) Microminiature image pickup device described in Claim 1 wherein said first electronic component is mounted in said cavity in a bare chip state.

4. (Amended) Microminiature image pickup device described in Claim 1 wherein said image pickup device is a CCD device.

5. (Amended) Microminiature image pickup device described in Claim 1 wherein said connection member is TAB tape.

Please add new claims 6-11 as follows:

-- 6. (New) Microminiature image pickup device described in Claim 2 wherein said first electronic component is mounted in said cavity in a bare chip state.

7. (New) Microminiature image pickup device described in Claim 2 wherein said image pickup device is a CCD device.

8. (New) Microminiature image pickup device described in Claim 3 wherein said image pickup device is a CCD device.

9. (New) Microminiature image pickup device described in Claim 2 wherein said connection member is TAB tape.

10. (New) Microminiature image pickup device described in Claim 3 wherein said connection member is TAB tape.

11. (New) Microminiature image pickup device described in Claim 4 wherein said connection member is TAB tape. --